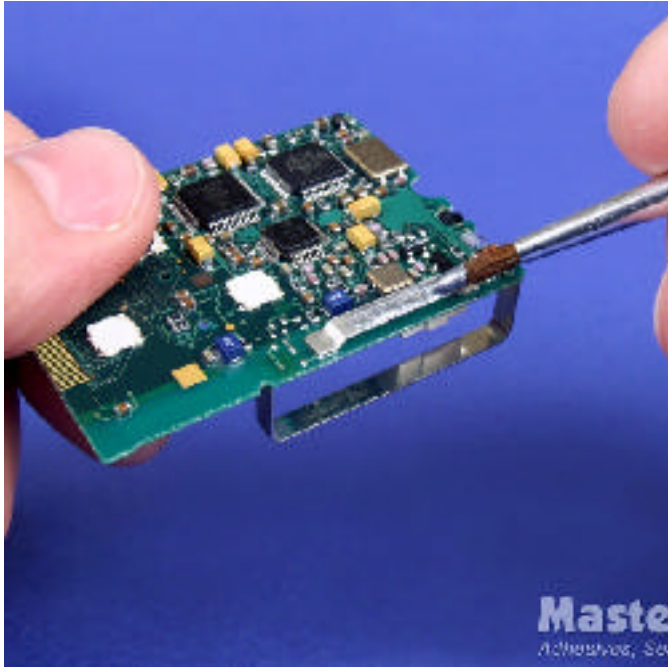


## **Silver Conductive Epoxy Meets NASA Low Outgassing Standards**



Master Bond EP21TDCS-LO is an electrically conductive silver-filled epoxy that passes ASTM 595 for NASA low outgassing specifications. It is widely used for demanding applications in the electronic, electrical, computer, semiconductor, aerospace, and optical industries. The adhesive cures at room temperature in 24-48 hours and in just one to two hours at 200°F, producing tough high strength bonds. It features tensile shear strength of more than 1,800 psi, T-peel of greater than 5 pli, and outstanding adhesion to similar and dissimilar substrates. The volume resistivity of the system is less than  $10^{-3}$  ohm-cm. Serviceable over the exceptionally wide range of 4 K to 275°F, EP21TDCS-LO is suitable for cryogenic applications. It withstands thermal cycling and is resistant to chemicals, including water, oil, and most organic solvents.

The epoxy offers a simple 1:1 mixing ratio by weight or volume. With its low drip formula, EP21TDCS-LO can be conveniently applied with a syringe, knife, spatula, or trowel to vertical surfaces without sagging and only contact pressure is required for curing. Syringes have a three month shelf life and glass jars have a six month shelf life, if stored at room temperature. EP21TDCS-LO is available in premixed and frozen syringes, as well as in metal containers.

**Source URL (retrieved on 01/29/2015 - 11:21pm):**

<http://www.mdtmag.com/product-releases/2011/02/silver-conductive-epoxy-meets-nasa-low-outgassing-standards>